

## LM185QML Adjustable Micropower Voltage References

Check for Samples: [LM185QML](#)

### FEATURES

- Adjustable from 1.24V to 5.30V
- Operating Current of 10 $\mu$ A to 20mA
- 1 $\Omega$  Dynamic Impedance
- Low Temperature Coefficient

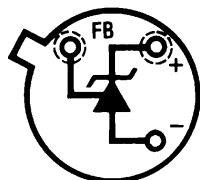
### DESCRIPTION

The LM185 are micropower 3-terminal adjustable band-gap voltage reference diodes. Operating from 1.24 to 5.3V and over a 10 $\mu$ A to 20mA current range, they feature exceptionally low dynamic impedance and good temperature stability. On-chip trimming is used to provide tight voltage tolerance. Since the LM185 band-gap reference uses only transistors and resistors, low noise and good long-term stability result.

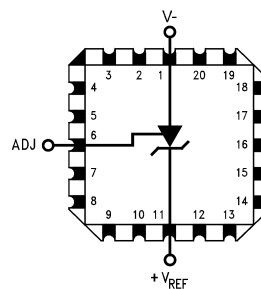
Careful design of the LM185 has made the device tolerant of capacitive loading, making it easy to use in almost any reference application. The wide dynamic operating range allows its use with widely varying supplies with excellent regulation.

The extremely low power drain of the LM185 makes it useful for micropower circuitry. This voltage reference can be used to make portable meters, regulators or general purpose analog circuitry with battery life approaching shelf life. Further, the wide operating current allows it to replace older references with a tighter tolerance part.

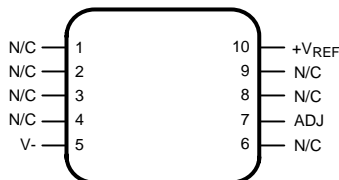
### Connection Diagrams



**Figure 1. PFM Metal Can Package (Bottom View)**  
See Package Number NDV0003H



**Figure 2. 20-Leadless Chip Carrier (Top View)**  
See Package Number NAJ0020A



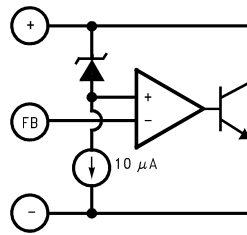
**Figure 3. 10-Lead CLGA (Top View)**  
See Package Number NAC0010A



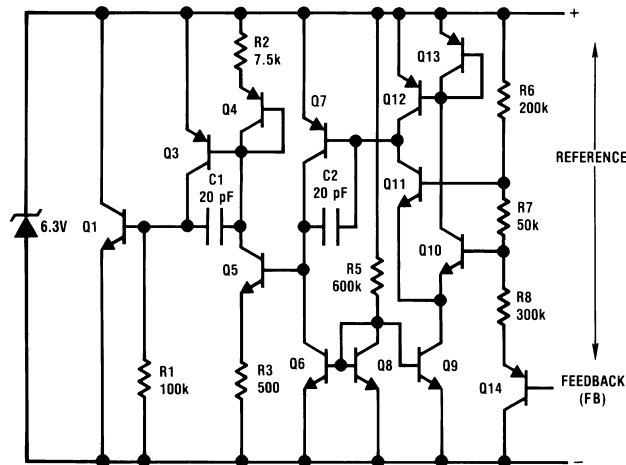
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.

**Block Diagram**



**Schematic Diagram**



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**Absolute Maximum Ratings<sup>(1)</sup>**

Reverse Current		30mA	
Forward Current		10mA	
Operating Temperature Range		-55°C ≤ T <sub>A</sub> ≤ 125°C	
Storage Temperature		-55°C ≤ T <sub>A</sub> ≤ 150°C	
Maximum Junction Temperature T <sub>Jmax</sub>		150°C	
Lead Temperature (soldering, 10 seconds)		300°C	
Thermal Resistance	θ <sub>JA</sub>	LCCC Package (Still Air)	100°C/W
		LCCC Package (500LF/Min Air flow)	73°C/W
		Metal Can Package (Still Air)	300°C/W
		Metal Can Package (500LF/Min Air flow)	139°C/W
		CLGA Package (Still Air)	194°C/W
		CLGA Package (500LF/Min Air flow)	128°C/W
	θ <sub>JC</sub>	LCCC Package	25°C/W
		Metal Can Package	57°C/W
CLGA Package		23°C/W	
Package Weight (Typical)	LCCC Package	TBD	
	Metal Can Package	TBD	
	CLGA Package	210mg	
ESD Tolerance <sup>(2)</sup>		500V	

- (1) Absolute Maximum Ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions under which operation of the device is intended to be functional. For guaranteed specifications and test conditions, see the Electrical Characteristics.
- (2) Human body model, 1.5 kΩ in series with 100 pF.

**Table 1. Quality Conformance Inspection  
Mil-Std-883, Method 5005 - Group A**

Subgroup	Description	Temp °C
1	Static tests at	25
2	Static tests at	125
3	Static tests at	-55
4	Dynamic tests at	25
5	Dynamic tests at	125
6	Dynamic tests at	-55
7	Functional tests at	25
8A	Functional tests at	125
8B	Functional tests at	-55
9	Switching tests at	25
10	Switching tests at	125
11	Switching tests at	-55
12	Settling time at	25
13	Settling time at	125
14	Settling time at	-55

**LM185B Electrical Characteristics DC Parameters**

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
$V_{Ref}$	Reference Voltage	$I_R = 100\mu A$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$I_R = 9\mu A$		1.228	1.252	V	1
		$I_R = 10\mu A$		1.215	1.255	V	2, 3
		$I_R = 1mA$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$I_R = 20mA$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 100\mu A$		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 45\mu A$		1.288	1.252	V	1
		$V_R = 5.3V, I_R = 50\mu A$		1.215	1.255	V	2, 3
		$V_R = 5.3V, I_R = 1.0mA$		1.288	1.252	V	1
				1.215	1.255	V	2, 3
$V_R = 5.3V, I_R = 20mA$		1.288	1.252	V	1		
		1.215	1.255	V	2, 3		
$\Delta V_{Ref}/\Delta I_R$	Reference Voltage Change with Current	$9\mu A \leq I_R \leq 1mA$			1.0	mV	1
		$10\mu A \leq I_R \leq 1mA$			1.5	mV	2, 3
		$1mA \leq I_R \leq 20mA$			10	mV	1
					20	mV	2, 3
		$V_R = 5.3V, 45\mu A \leq I_R \leq 1mA$			1.0	mV	1
		$V_R = 5.3V, 50\mu A \leq I_R \leq 1mA$			1.5	mV	2, 3
		$V_R = 5.3V, 1mA \leq I_R \leq 20mA$			10	mV	1
			20	mV	2, 3		
$\Delta V_{Ref}/\Delta V_O$	Reference Voltage Change with Output Voltage	$V_R = 5.3V, I_R = 100\mu A$			3.0	mV	1
					6.0	mV	2, 3
$I_F$	Feedback Current	$I_R = 9\mu A$			20	nA	1
					25	nA	2, 3
		$I_R = 10\mu A$			20	nA	1
					25	nA	2, 3
		$V_R = 5.3V, I_R = 45\mu A$			20	nA	1
		$V_R = 5.3V, I_R = 50\mu A$			25	nA	2, 3
		$V_R = 5.3V, I_R = 20mA$			20	nA	1
			25	nA	2, 3		
$I_C$	Minimum Operating Current	$V_R = V_{Ref}$	See <sup>(1)</sup>		9.0	$\mu A$	1
			See <sup>(1)</sup>		10	$\mu A$	2, 3
		$V_R = 5.3V$	See <sup>(1)</sup>		45	$\mu A$	1
			See <sup>(1)</sup>		50	$\mu A$	2, 3

(1) Functional test.

**LM185BY Electrical Characteristics DC Parameters**

Symbol	Parameter	Conditions	Notes	Min	Max	Unit	Sub-groups
V <sub>Ref</sub>	Reference Voltage	I <sub>R</sub> = 100μA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		I <sub>R</sub> = 9μA		1.228	1.252	V	1
		I <sub>R</sub> = 10μA		1.215	1.255	V	2, 3
		I <sub>R</sub> = 1mA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		I <sub>R</sub> = 20mA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 100μA		1.228	1.252	V	1
				1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 45μA		1.288	1.252	V	1
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 50μA		1.215	1.255	V	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 1.0mA		1.288	1.252	V	1
	1.215		1.255	V	2, 3		
V <sub>R</sub> = 5.3V, I <sub>R</sub> = 20mA		1.288	1.252	V	1		
		1.215	1.255	V	2, 3		
ΔV <sub>Ref</sub> /ΔI <sub>R</sub>	Reference Voltage Change with Current	9μA ≤ I <sub>R</sub> ≤ 1mA			1.0	mV	1
		10μA ≤ I <sub>R</sub> ≤ 1mA			1.5	mV	2, 3
		1mA ≤ I <sub>R</sub> ≤ 20mA			10	mV	1
					20	mV	2, 3
		V <sub>R</sub> = 5.3V, 45μA ≤ I <sub>R</sub> ≤ 1mA			1.0	mV	1
		V <sub>R</sub> = 5.3V, 50μA ≤ I <sub>R</sub> ≤ 1mA			1.5	mV	2, 3
		V <sub>R</sub> = 5.3V, 1mA ≤ I <sub>R</sub> ≤ 20mA			10	mV	1
			20	mV	2, 3		
ΔV <sub>Ref</sub> / ΔV <sub>O</sub>	Reference Voltage Change with Output Voltage	V <sub>R</sub> = 5.3V, I <sub>R</sub> = 100μA			3.0	mV	1
					6.0	mV	2, 3
I <sub>F</sub>	Feedback Current	I <sub>R</sub> = 9μA			20	nA	1
		I <sub>R</sub> = 10μA			25	nA	2, 3
		I <sub>R</sub> = 20mA			20	nA	1
					25	nA	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 45μA			20	nA	1
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 50μA			25	nA	2, 3
		V <sub>R</sub> = 5.3V, I <sub>R</sub> = 20mA			20	nA	1
			25	nA	2, 3		
I <sub>C</sub>	Minimum Operating Current	V <sub>R</sub> = V <sub>Ref</sub>	See <sup>(1)</sup>		9.0	μA	1
			See <sup>(1)</sup>		10	μA	2, 3
		V <sub>R</sub> = 5.3V	See <sup>(1)</sup>		45	μA	1
			See <sup>(1)</sup>		50	μA	2, 3
T <sub>C</sub>	Temperature Coefficient		See <sup>(2)</sup>		50	PPM/°C	1, 2, 3

(1) Functional test.

(2) The average temperature coefficient is defined as the maximum deviation of reference voltage, at all measured temperatures between the operating T<sub>Min</sub> & T<sub>Max</sub>, divided by (T<sub>Max</sub> - T<sub>Min</sub>). The measured temperatures (T<sub>Measured</sub>) are -55°C, 25°C, & 125°C or ΔV<sub>Ref</sub> / (T<sub>Max</sub> - T<sub>Min</sub>)

Typical Performance Characteristics

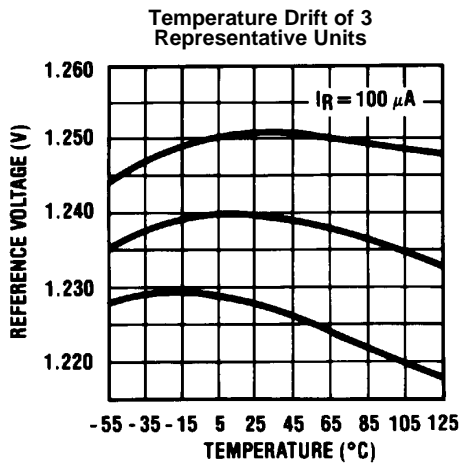


Figure 4.

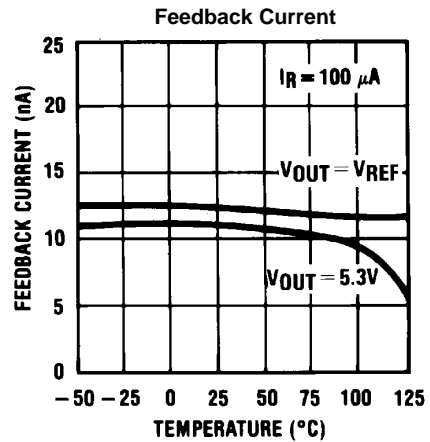


Figure 5.

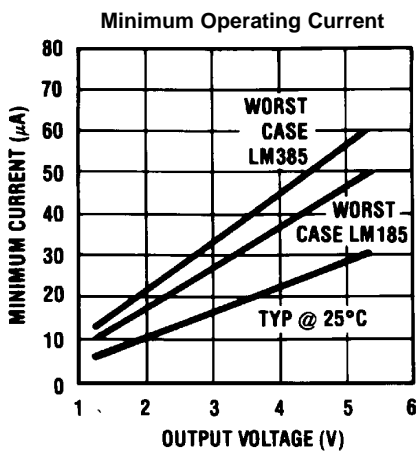


Figure 6.

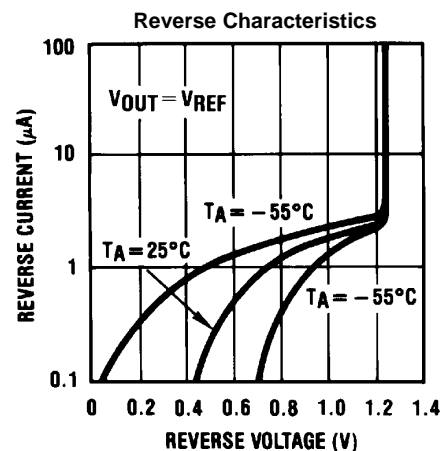


Figure 7.

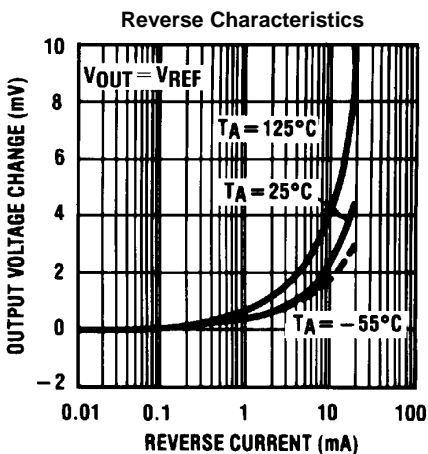


Figure 8.

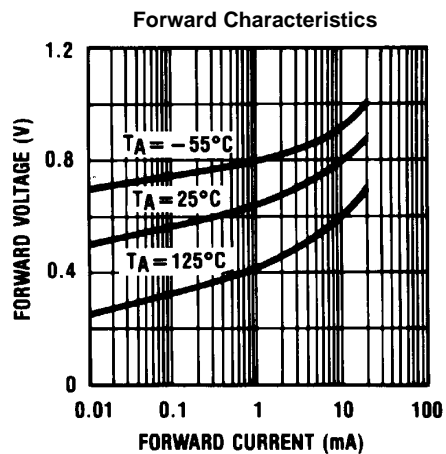


Figure 9.

Typical Performance Characteristics (continued)

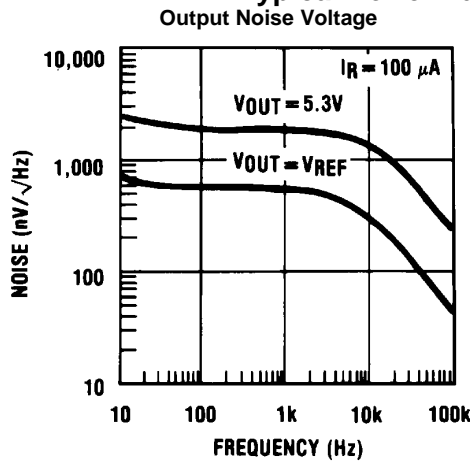


Figure 10.

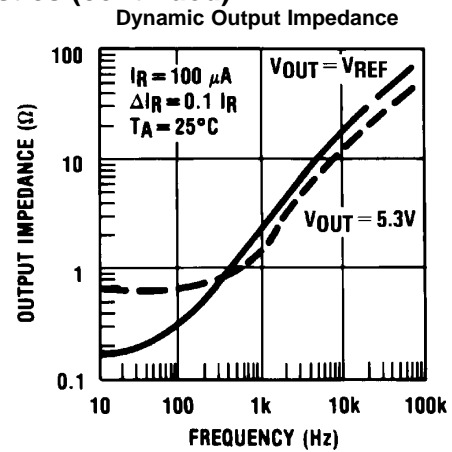


Figure 11.

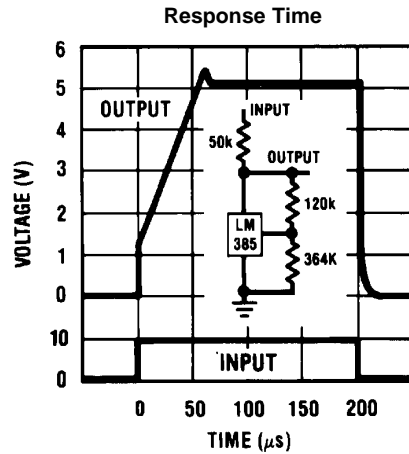


Figure 12.

Temperature Coefficient Typical LM185

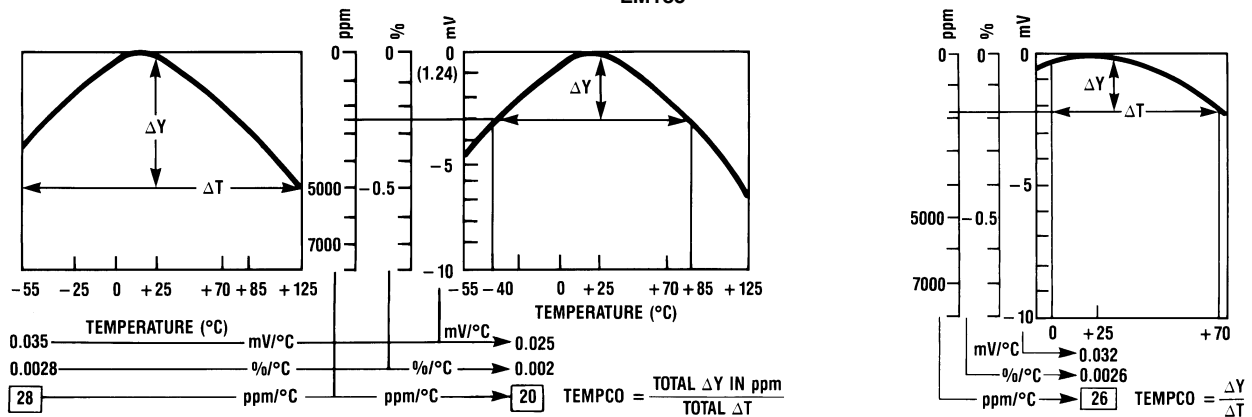


Figure 13.





Voltage Level Detector

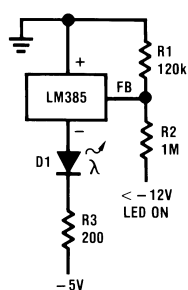


Figure 20.

Voltage Level Detector

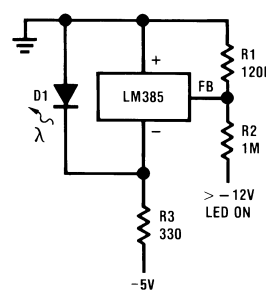


Figure 21.

Fast Positive Clamp  
 $2.4V + \Delta V_{D1}$

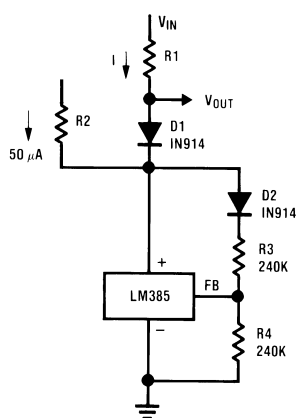


Figure 22.

Bidirectional Clamp  
 $\pm 2.4V$

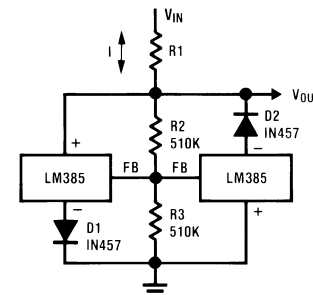


Figure 23.

Bidirectional Adjustable Clamp  
 $\pm 1.8V$  to  $\pm 2.4V$

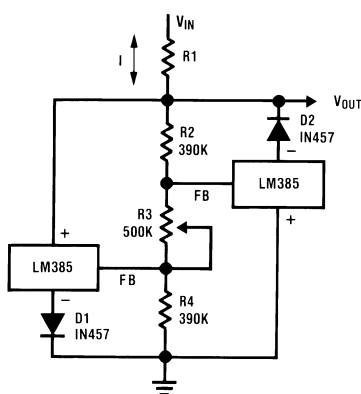


Figure 24.

Bidirectional Adjustable Clamp  
 $\pm 2.4V$  to  $\pm 6V$

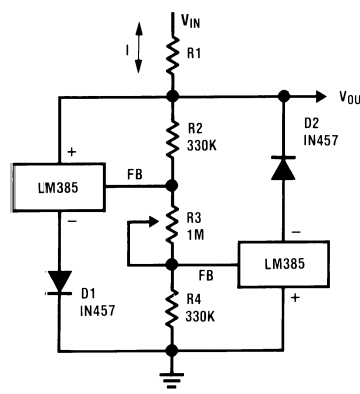


Figure 25.

\*D1 can be any LED,  $V_F=1.5V$  to  $2.2V$  at  $3mA$ . D1 may act as an indicator. D1 will be on if  $I_{THRESHOLD}$  falls below the threshold current, except with  $I=0$ .

Simple Floating Current Detector

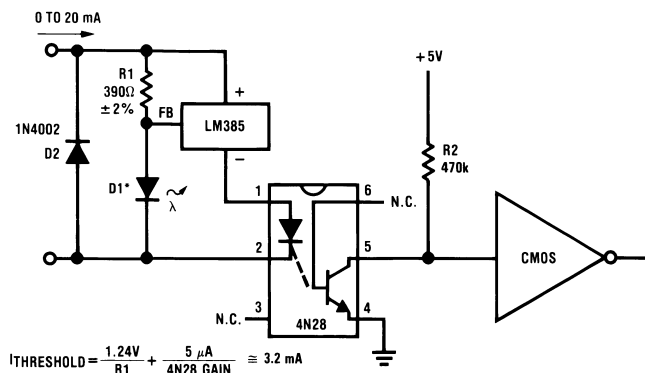


Figure 26.

Precision Floating Current Detector

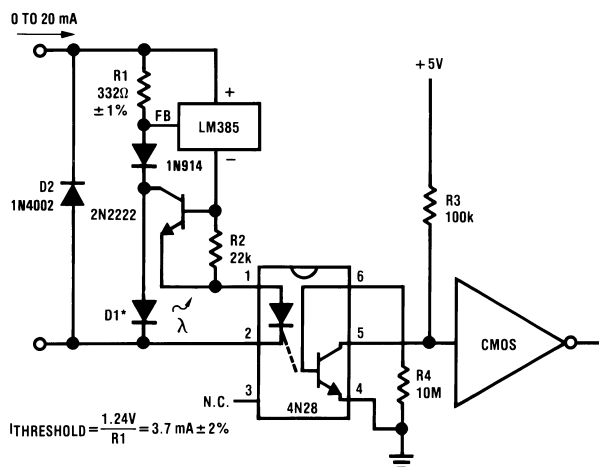


Figure 27.

Current Source

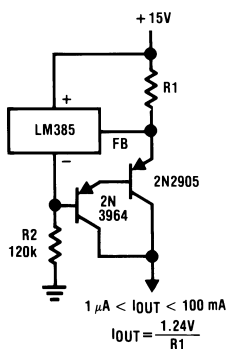


Figure 28.

Centigrade Thermometer, 10mV/°C

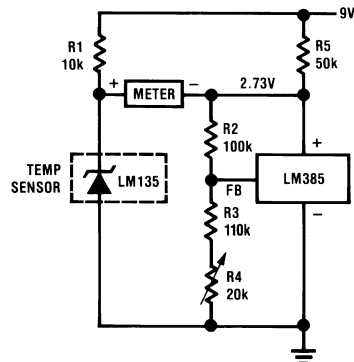
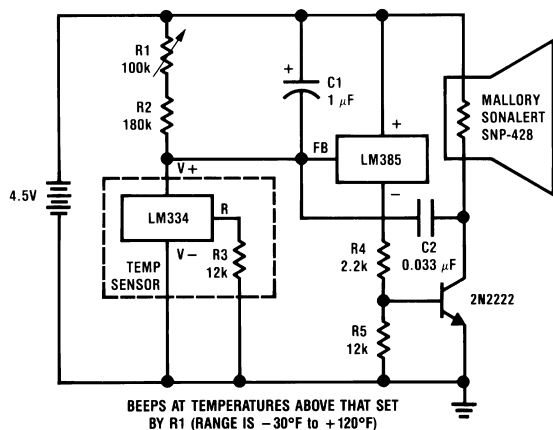


Figure 29.

Freezer Alarm



BEEPS AT TEMPERATURES ABOVE THAT SET BY R1 (RANGE IS -30°F to +120°F)

Figure 30.

$$V_{OUT} = 1.24 \left( \frac{R3}{R2} + 1 \right)$$

1.2V Reference

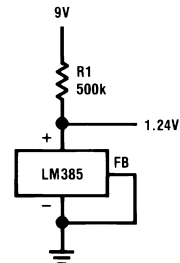
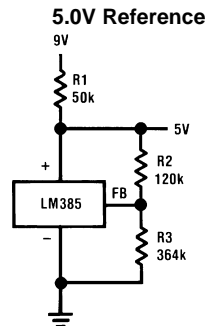


Figure 31.





**Figure 32.**

**REVISION HISTORY SECTION**

Released	Revision	Section	Originator	Changes
11/08/05	A	New Release, Corporate format	L. Lytle	2 MDS data sheets converted into one Corp. data sheet format. MNLM185B-X Rev 0B0 and MNLM185BY-X Rev 0B0 will be archived.
04/06/06	B	Ordering Information Table, WG Connection Diagram, Absolute Maximum Ratings Section, Physical Dimensions Section	R. Malone	Added NSID, Connection Diagram, Physical Dimension Dwg, Thermal Resistance and Package Weight for NAC package. Revision A will be Archived.
06/12/08	C	LM185B and LM185BY Electrical Section	Larry McGee	Correct IC test, $V_R = V_{REF}$ condition, subgroup 1, 2, 3 moved limits to the maximum column. Revision B will be Archived.
03/27/13	D	All		Changed layout of National Data Sheet to TI format.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
5962-9091402QYA	ACTIVE	CFP	NAC	10	54	TBD	Call TI	Call TI	-55 to 125	LM185BWG /883 Q 5962-90914 02QYA ACO 02QYA >T	
LM185BWG/883	ACTIVE	CFP	NAC	10	54	TBD	Call TI	Call TI	-55 to 125	LM185BWG /883 Q 5962-90914 02QYA ACO 02QYA >T	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

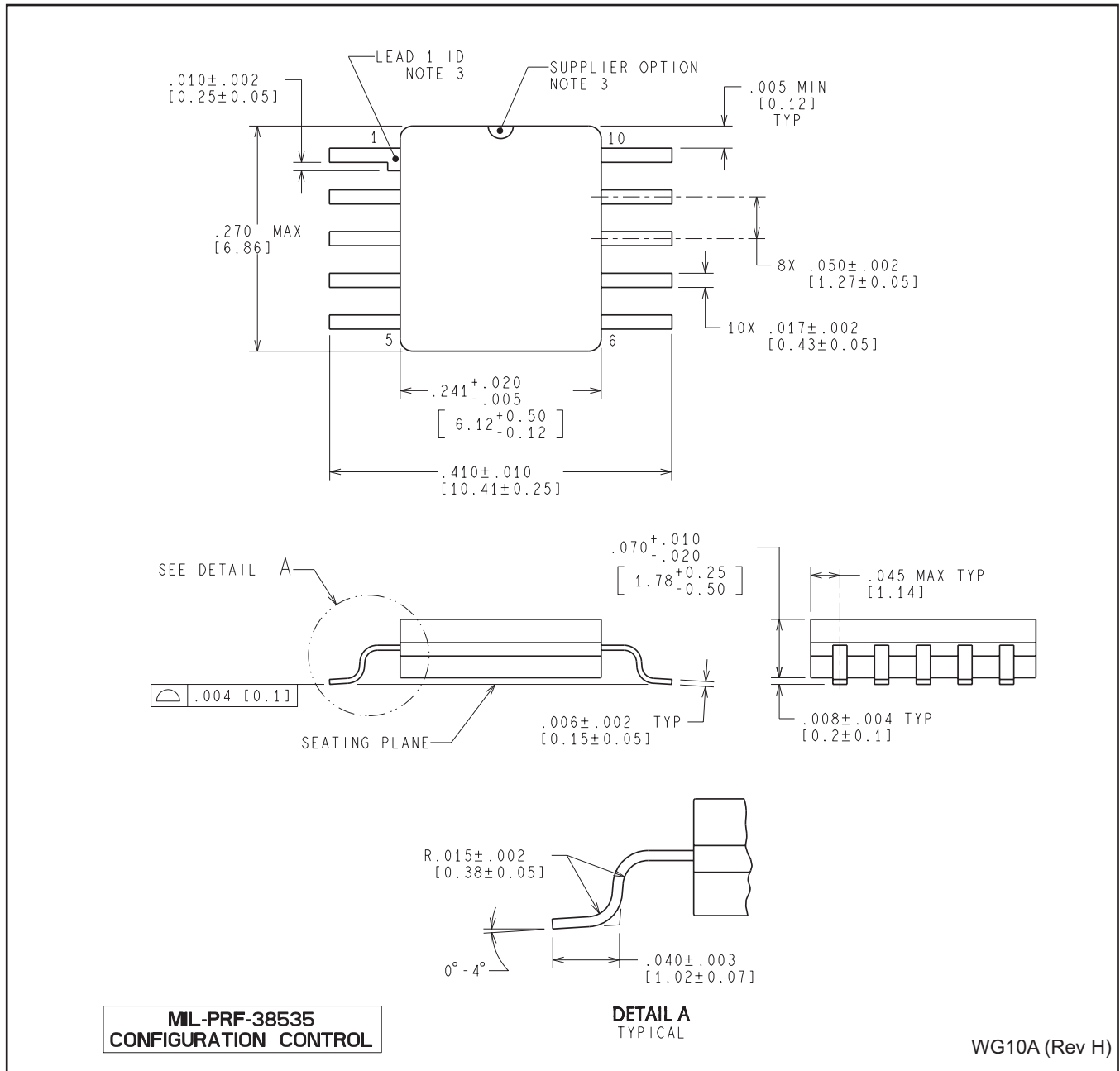
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

NAC0010A



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)